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REV

DESCRIPTION

APPROVED

DATE

P1

RELEASE FOR FABRICATION

DM

04/10/14

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PRODUCTION RELEASE

DM

02/13/15

NOTES:

UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).

MATERIAL: (USE CHECKED ITEMS FOR MATERIAL)

2. BOARD MATERIAL:

(X) FR4 (RgHS COMPLIANT) OR EQUIVALENT

() ISOLA-FR40BHR

() NIELCO-4000-1.3 OR EQUIVALENT

() 370HR (RgHS COMPLIANT) OR EQUIVALENT

() ROGERS 4350B

() ROGERS 4003C

() OTHER _____

3. THE PCB SHALL BE FABRICATED TO IPC-6012, TYPE X, CLASS 2.

WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.

4. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796 WITH FLAMMABILITY RATING OF 94V-0.

5. OVERALL BOARD THICKNESS REFER TO LAMINATION DIAGRAM. TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. IT IS TO BE MEASURED FROM TOP PCB METAL TO BOTTOM PCB METAL UNLESS OTHERWISE SPECIFIED.

6. BOW & TWIST NOT TO EXCEED 0.0075 IN. (0.75%) PER LINEAR INCH.

BOW & TWIST SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.

TOOLING:

(USE CHECKED ITEMS FOR TOOLING)

7. PHOTO ETCH CIRCUITRY PER ENCLOSED GERBER RS274X OR ODB++ FORMAT FILE.

DRILL LOCATION AND SIZE CONTROLLED BY EXCELLON CNC DRILL FILE.

8. IF STATED IN THE LAMINATION DIAGRAM, THE DIELECTRIC THICKNESS OF ANY CONTROLLED IMPEDANCE LAYER IS FOR REFERENCE ONLY. FINAL ACCEPTANCE SHALL BE DETERMINED BY THESE LAYERS HAVING A CHARACTERISTIC IMPEDANCE OF +/-10% OHMS AS STATED IN THE LAMINATION DIAGRAM. THE VENDOR CAN MAKE ADJUSTMENTS AS LONG AS THE STATED IMPEDANCE AND OVERALL BOARD THICKNESS IS MAINTAINED. ANY ADJUSTMENT MADE TO TRACE WIDTH OR SPACING MUST HAVE PRIOR WRITTEN APPROVAL FROM MAXIM.

9. ALL TRACES FILLETED OPTION TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS. UNLESS OTHERWISE SPECIFIED:

() FILLETED

(X) NOT FILLETED

10. LAYER TO LAYER REGISTRATIONS SHALL BE WITHIN .003 INCHES.

LEGEND TO LEGEND +/- 0.007 INCHES

FINISH:

(USE CHECKED ITEMS FOR PLATING)

11. PLATING SPECIFICATION:

() STARTING COPPER WEIGHT FOR OUTER LAYERS CAN BE (0.5 OZ), THE FINISH COPPER WEIGHT IS (1 OZ).

FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT

THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (1 OZ)

UNLESS OTHERWISE SPECIFIED

(X) STARTING COPPER WEIGHT FOR OUTER LAYERS CAN BE (1 OZ), THE FINISH COPPER WEIGHT IS (2 OZ).

FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT,

THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ).

UNLESS OTHERWISE SPECIFIED

() STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (2 OZ), THE FINISH COPPER WEIGHT IS (2 OZ)MINIMUM.

FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (2 OZ) AS A STARTING WEIGHT,

THE STARTING WEIGHT CAN BE (2 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ).

UNLESS OTHERWISE SPECIFIED

() OTHER _____

12. CHECK ALL THAT APPLY

() FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 3-8 MICRO INCHES OVER

100 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.

(X) LEAD FREE AND RgHS COMPLIANT OR EQUIVALENT LEAD FREE PLATING

() ELECTRODEPOSITED HARD GOLD PLATE, TYPE 1 (99.7% MIN. GOLD), GRADE C (KNOPF HARDNESS 130-200), CLASS 1 (50-100 MICRO INCHES THICK) IN ACCORDANCE WITH MIL-G-45204C.

GENERAL SURFACING REQUIREMENTS MUST MEET ANSI/IPC-A-600(CURRENT REV) SECTION 4.0,

CLASS 3 (50-100 MICROINCHES THICK) OVER ELECTRODEPOSITED NICKEL PLATE

IN ACCORDANCE WITH ANSI/IPC-A-600D, SECTION 4.0, CLASS 3 (200-600 MICROINCHES THICK).

() FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 2-5 MICRO INCHES OVER

118-236 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.

() FINGERS TO BE GOLD PLATED.

() OTHER _____

13. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN .005 DTP.

MINIMUM BARREL PLATING OF .001 IN. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR

SO AS TO HINDER PROPER SOLDER WICKING.

14. CHECK ALL THAT APPLY

(X) GREEN SOLDERMASK OVER BARE COPPER/BARE GOLD (BOTH SIDES) WITH LIQUID PHOTO IMAGEABLE INK (LPI)

PER ARTWORK.

() GREEN TAYPO PSR-4000

() OTHER _____

15. CHECK ALL THAT APPLY

(X) APPLY SILKSCREEN USING A NON-CONDUCTIVE, WHITE EPOXY

BASED INK PER ARTWORK.

() OTHER _____

16. VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYWW ONLY

TESTING:

17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE.

(REQUIRED UNLESS OTHERWISE SPECIFIED IN QUOTE)

THE PCB SHALL HAVE A VERIFICATION STAMP.

18. A TIME DOMAIN REFLECTOMETER REPORT FOR EACH IMPEDANCE CONTROLLED LAYER AND A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT.

MISCELLANEOUS:

19. FOR ALL DRILL INFORMATION REFER TO DRILL CHART:

() NON-CONDUCTIVE EPOXY FILL AND CAP ALL 0.000X INCH DRILLED VIAS.

() SILVER FILL AND CAP ALL 0.000X INCH DRILLED VIAS.

20. IF PRESENT, ALL MICRO VIAS LESS THAN 0.006 INCHES PHS WHEN USED AS VIP (VIA IN PAD) OR STACKED

TO BE PLATED SHUT WITH COPPER, UNLESS OTHERWISE SPECIFIED.

21. FINISHED SURFACE CONTACTS AND FILLED VIAS TO BE FREE OF ANY PITS, SCRATCHES, PROBE MARKS

OR OTHER DEFORMITIES THAT COULD EFFECT THE APPEARANCE AND PERFORMANCE OF THE CONTACT

SURFACE. CONTACTS ARE TO BE AS FLAT AS POSSIBLE. NOT TO EXCEED +/- 0.001" OF FLATNESS.

22. THEIVING:

() SUPPLIER MAY ADD THEIVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.

(X) SUPPLIER MAY NOT ADD THEIVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.

23. PENNUT

() PENNUTS TO BE INSTALLED BY SUPPLIER.

() PENNUTS NOT TO BE INSTALLED BY SUPPLIER.

(X) NOT APPLICABLE

24. DESIGN HAS INTENTIONAL SHORT OF SGND, PGND1 & PGND2 ON PWR (LAYER 3) LAYER.

MAXIM

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HARDWARE NAME:MAX17521_EVKIT_A

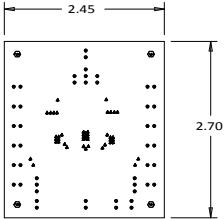
HARDWARE NUMBER:

DESIGNER:MANIKANDAN S

DATE: 02/13/15

REV:02/13/15

FILE NOTES



IMPEDANCE TABLE			
LAYER	50 OHM	100 OHM DIFF TRACE / SPACE	75 OHM DIFF TRACE / SPACE
TOP	-	-	-
X	-	-	-
X	-	-	-
BOTTOM	-	-	-

NOTE: DO NOT PUT THIS TABLE INTO A FILE THAT REFERENCE YOURSelves FROM MAXIM FILES

LAMINATION DIAGRAM				
LAYER NUMBER	LAYER NAME	FINISHED CU WEIGHT (OZ)	DIELECTRIC THICKNESS (in.)	DIELECTRIC MATERIAL
1	TOP	2		FOIL
			TBD	FR4(RgHS)/EQIV
2	GND	1		
			TBD	FR4(RgHS)/EQIV
3	PWR	1		
			TBD	FR4(RgHS)/EQIV
4	BOTTOM	2		FOIL

THE FINISHED PCB THICKNESS TO BE: 0.0625" +/- 0.010"

DRILL CHART: TOP to BOTTOM					
ALL UNITS ARE IN MILS					
FIGURE	SIZE	TOLERANCE	PLATED	QTY	NOTES
▲	12.0	+3.0/-10.0	PLATED	46	
⊙	39.37	+3.0/-3.0	PLATED	30	
⊙	43.31	+3.0/-3.0	PLATED	17	
⊙	125.0	+3.0/-3.0	PLATED	4	

TOLERANCES UNLESS OTHERWISE SPECIFIED

FRACTIONS

DECIMALS

ANGLES

MATERIAL:

SEE NOTES

FINISH:

SEE NOTES

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DRAWN BY:MANIKANDAN S

DATE: 02/13/15

CHECKED BY: DIPANKAR M

DATE: 02/13/15

APPR. BY: DIPANKAR M

DATE: 02/13/15

APPR. BY:

DATE:

maxim integrated™

HARDWARE NAME:

MAX17521_EVKIT_A

HARDWARE NUMBER:

NOT TO SCALE

TEMPLATE REV:2.1

SHEET 1 OF 1

REV

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